ASSOCIATION CONNECTING LECTRONICS INDUSTRIES INDUSTRIES INDUSTRIES	nockburn, Illinois, A	All rights reserved un ntions.	nder both	This docume evel parts, t	ent is a declaratio he declaration en	n of the substanc compasses all lo	es within the manufactur wer level materials for w	rer listed ite hich the ma	n. Note: if nufacturer	the item is an as has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute			* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
Supplier Information												
ompany name* Company unique ID				Unique ID Authority				Response Date*				
onsemi	emi								2024-04-26			
Contact Name	Title - Contact]	Phone - Contact*				Email - Contact*			
Product-Env-Stewards	s Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
thorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Enviro Compliance					NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mf	r Item Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		eight*	UOM	Unit Type	
NT	NTTFS4930NTAG NFET U8FL 30V 23		23A 23MOHM		2024-04-26		MY1	29	.38	mg	Each	
Manufacturing Proccess Information												
Terminal Plating / Grid Array Material	Terminal Base Alloy J-ST		STD-020 MSL	Rating	Peak Process Body Temperature		ture Max Time at Peak	Temperatu	e Numbe	er of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy 1					260	С	30	second	3			
Comments												
evel 1 - maximum time at peak temperature duri	ng soldering is 10-3	30 seconds										
for more information regarding material compos	sition please refer to	o page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company that agreement, will be the sole and exclusive	lease indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, admium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part ontains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall necompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, s of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. To may acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not idependently verified information provided by others, Supplier agrees that a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the ertification in the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the 'arranty' rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.								
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).						
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the				
Supplier Digital Signature	astislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	0.38	mg	Supplier	Zinc (Zn)	7440-66-6		0.0005	mg
			Supplier	Iron (Fe)	7439-89-6		0.0089	mg
			Supplier	Copper (Cu)	7440-50-8		0.3705	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0001	mg
Die	0.3	mg	Supplier	Silicon (Si)	7440-21-3		0.3	mg
Die Attach Solder	0.65	mg	Supplier	Silver (Ag)	7440-22-4		0.0162	mg
			А	Lead (Pb)	7439-92-1	7a	0.6012	mg
			Supplier	Tin (Sn)	7440-31-5		0.0325	mg
Lead Frame	12.41	mg	Supplier	Silver (Ag)	7440-22-4		0.0074	mg
			Supplier	Iron (Fe)	7439-89-6		0.0124	mg
			Supplier	Copper (Cu)	7440-50-8		12.3864	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0037	mg
Mold Compound-Black	15.0	mg		Epoxy resin	proprietary data		1.125	mg
			Supplier	Phenolic Resin	Proprietary Data		0.375	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.125	mg
			Supplier	Carbon Black (C)	1333-86-4		0.075	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		12.3	mg
Plating	0.6	mg	Supplier	Tin (Sn)	7440-31-5		0.6	mg
Wire Bond - Cu	0.04	mg	Supplier	Copper (Cu)	7440-50-8		0.04	mg